

WHAT IS CLAIMED IS:

1. A multi-color light emitting diode package mounted thereon with at least three light emitting diodes comprising:

5 a substrate formed at an upper surface thereof with a pattern including three first terminals, and a single second terminal;

10 first and second light emitting diodes among the at least three light emitting diodes, the first and second light emitting diodes being mounted on a conductive mount pattern extending from the second terminal, and all formed at their upper surfaces with first and second electrodes; and

15 a single zener diode chip having two zener diodes, the zener diode chip being mounted on the conductive mount pattern, and formed at a lower surface thereof with a second electrode, and at an upper surface thereof with two first electrodes,

20 wherein the second electrode of the first light emitting diode and one of the first electrodes provided in the single zener diode chip are connected to an associated one of the first terminals, and the second electrode of the second light emitting diode and the other one of the first electrodes provided in the single zener diode chip are connected to another associated one of the first terminals.

2. The package as set forth in claim 1, wherein the first and second light emitting diodes are green and blue light emitting diodes, respectively.

5 3. The package as set forth in claim 2, wherein:

the other remaining light emitting diode among the at least three light emitting diodes is a red light emitting diode, which is formed at an upper surface thereof with a first electrode, and at a lower surface thereof with a second
10 electrode;

the red light emitting diode is mounted on the substrate so that it is positioned on a conductive mount pattern extending from the other remaining first terminal among the three first terminals, which is not connected with the first
15 electrodes of the single zener diode chip; and

the second electrode of the red light emitting diode is connected to the second terminal or the mount pattern extending from the second terminal.

20 4. The package as set forth in claim 2, wherein:

the other remaining light emitting diode among the at least three light emitting diodes is a red light emitting diode, which is formed at an upper surface thereof with a second electrode, and at a lower surface thereof with a first

electrode;

the red light emitting diode is mounted on the substrate so that it is positioned on the conductive mount pattern extending from the second terminal; and

5 the second electrode of the red light emitting diode is connected to the other remaining first terminal among the three first terminals, which is not connected with the first electrodes of the single zener diode chip.

10 5. The package as set forth in claim 1, wherein the single zener diode chip comprises a first conductive substrate formed at a lower surface thereof with the second electrode, and two second conductive impurity areas defined at an upper portion of the first conductive substrate while being spaced
15 apart from each other, each second conductive impurity area being formed at an upper surface thereof with one of the first electrodes.

20 6. The package as set forth in claim 1, wherein the mount pattern extending from the second terminal is positioned at a central region of the substrate, and the first terminals and the second terminal are positioned at both side edges of the substrate.

7. The package as set forth in claim 2, wherein the red, blue and green light emitting diodes are arranged in a triangular pattern.

5 8. The package as set forth in claim 7, wherein the single zener diode chip is positioned adjacent to the blue and green light emitting diodes of the triangular pattern.

9. The package as set forth in claim 8, wherein:

10 the two first terminals connected to the two first electrodes of the single zener diode chip, respectively, are positioned at both side edges of the substrate adjacent to the blue and green light emitting diodes, respectively; and

15 the other remaining first terminal and the second terminal are positioned at both side edges of the substrate adjacent to the red light emitting diode, respectively.

20 10. The package as set forth in claim 1, wherein the first terminals are cathode terminals, and the second terminal is an anode terminal.